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TinyLogic UHS Dual Buffer with 3-STATE Outputs

NC7WZ126

Description

The NC7WZ126 is a Dual Non-Inverting Buffer with independent active HIGH enables for the 3-STATE outputs. The Ultra High Speed device is fabricated with advanced CMOS technology to achieve superior switching performance with high output drive while maintaining low static power dissipation over a broad V_{CC} operating range. The device is specified to operate over the 1.65 V to 5.5 V V_{CC} operating range. The inputs and outputs are high impedance when V_{CC} is 0 V. Inputs tolerate voltages up to 5.5 V independent of V_{CC} operating range. Outputs tolerate voltages above V_{CC} when in the 3-STATE condition.

Features

- Space Saving US8 Surface Mount Package
- MicroPak™ Pb-Free Leadless Package
- Ultra High Speed: t_{PD} 2.6 ns Typ. into 50 pF at 5 V V_{CC}
- High Output Drive: ± 24 mA at 3 V V_{CC}
- Broad V_{CC} Operating Range: 1.65 V to 5.5 V
- Matches the Performance of LCX when Operated at 3.3 V V_{CC}
- Power Down High Impedance Inputs / Outputs
- Overvoltage Tolerant Inputs Facilitate 5 V to 3 V Translation
- Outputs are Overvoltage Tolerant in 3-STATE Mode
- Patented Noise / EMI Reduction Circuitry Implemented
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

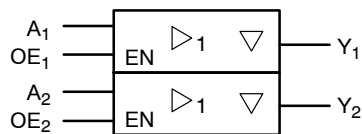
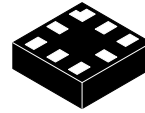
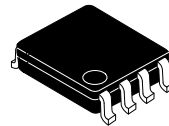


Figure 1. Logic Symbol

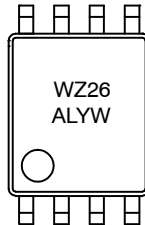
MARKING DIAGRAMS



UQFN8
1.6X1.6, 0.5P
CASE 523AY



US8
CASE 846AN



T6, WZ26 = Specific Device Code
 KK = 2-Digit Lot Run Traceability Code
 XY = 2-Digit Date Code Format
 Z = Assembly Plant Code
 A = Assembly Site
 L = Wafer Lot Number
 YW = Assembly Start Week

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 6.

Connection Diagrams

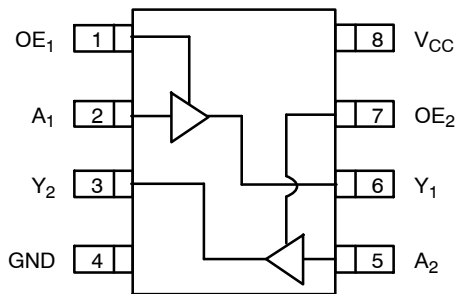


Figure 2. Connection Diagram
(Top View)

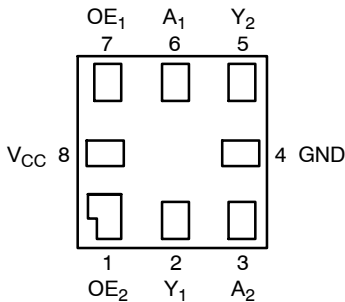


Figure 3. Pad Assignments for MicroPak
(Top Thru View)

PIN DESCRIPTIONS

Pin Names	Description
OE _n	Enable Inputs for 3-STATE Outputs
A _n	Inputs
Y _n	3-STATE Outputs

FUNCTION TABLE

Inputs		Output
OE	A _n	Y _n
H	L	L
H	H	H
L	L	Z
L	H	Z

H = HIGH Logic Level
L = LOW Logic Level
Z = 3-STATE

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter		Min	Max	Unit
V _{CC}	Supply Voltage		–0.5	6.5	V
V _{IN}	DC Input Voltage (Note 1)		–0.5	6.5	V
V _{OUT}	DC Output Voltage		–0.5	6.5	V
I _{IK}	DC Input Diode Current	V _{IN} < 0 V	–	–50	mA
I _{OK}	DC Output Diode Current	V _{OUT} < 0 V	–	–50	mA
I _{OUT}	DC Output Source / Sink Current		–	±50	mA
I _{CC} / I _{GND}	DC V _{CC} / GND Current		–	±100	mA
T _{STG}	Storage Temperature Range		–65	+150	°C
T _J	Junction Temperature under Bias		–	+150	°C
T _L	Junction Lead Temperature (Soldering, 10 Seconds)		–	+260	°C
P _D	Power Dissipation in Still Air		–	500	mW
			–	539	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. The input and output negative voltage ratings may be exceeded if the input and output diode current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V _{CC}	Supply Voltage Operating		1.65	5.5	V
	Supply Voltage Data Retention		1.5	5.5	
V _{IN}	Input Voltage		0	5.5	V
V _{OUT}	Output Voltage	Active State	0	V _{CC}	V
		3–State	0	5.5	V
T _A	Operating Temperature		–40	+85	°C
t _r , t _f	Input Rise and Fall Time	V _{CC} = 1.8 V ±0.15 V, 2.5 V ±0.2 V	0	20	ns/V
		V _{CC} = 3.3 V ±0.3 V	0	10	
		V _{CC} = 5.0 V ±0.5 V	0	5	
θ _{JA}	Thermal Resistance		–	250	°C/W
			–	232	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

2. Unused inputs must be held HIGH or LOW. They may not float.

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = +25°C			T _A = -40 to +85°C		Unit
				Min	Typ	Max	Min	Max	
V _{IH}	HIGH Level Input Voltage		1.65 to 1.95	0.65 V _{CC}	–	–	0.65 V _{CC}	–	V
			2.3 to 5.5	0.7 V _{CC}	–	–	0.7 V _{CC}	–	
V _{IL}	LOW Level Input Voltage		1.65 to 1.95	–	–	0.35 V _{CC}	–	0.35 V _{CC}	V
			2.3 to 5.5	–	–	0.3 V _{CC}	–	0.3 V _{CC}	
V _{OH}	HIGH Level Output Voltage	V _{IN} = V _{IH} or V _{IL}	I _{OH} = –100 µA	1.65	1.55	1.65	–	1.55	V
				2.3	2.2	2.3	–	2.2	
				3.0	2.9	3.0	–	2.9	
				4.5	4.4	4.5	–	4.4	
		V _{IN} = V _{IH} or V _{IL}	I _{OH} = –4 mA	1.65	1.29	1.52	–	1.29	
			I _{OH} = –8 mA	2.3	1.9	2.15	–	1.9	
			I _{OH} = –16 mA	3.0	2.4	2.80	–	2.4	
			I _{OH} = –24 mA	3.0	2.3	2.68	–	2.3	
			I _{OH} = –32 mA	4.5	3.8	4.20	–	3.8	
V _{OL}	LOW Level Output Voltage	V _{IN} = V _{IH} or V _{IL}	I _{OL} = 100 µA	1.65	–	0.0	0.10	–	V
				2.3	–	0.0	0.10	–	
				3.0	–	0.0	0.10	–	
				4.5	–	0.0	0.10	–	
		V _{IN} = V _{IH} or V _{IL}	I _{OL} = 4 mA	1.65	–	0.08	0.24	–	
			I _{OL} = 8 mA	2.3	–	0.10	0.3	–	
			I _{OL} = 16 mA	3.0	–	0.15	0.4	–	
			I _{OL} = 24 mA	3.0	–	0.22	0.55	–	
			I _{OL} = 32 mA	4.5	–	0.22	0.55	–	
I _{IN}	Input Leakage Current	V _{IN} = 5.5 V, GND	1.65 to 5.5	–	–	±0.1	–	±1	µA
I _{OZ}	3-STATE Output Leakage	V _{IN} = V _{IH} or V _{IL} 0 ≤ V _{OUT} ≤ 5.5 V	1.65 to 5.5	–	–	±0.5	–	±5	µA
I _{OFF}	Power Off Leakage Current	V _{IN} or V _{OUT} = 5.5 V	0.0	–	–	1	–	10	µA
I _{CC}	Quiescent Supply Current	V _{IN} = 5.5 V, GND	1.65 to 5.5	–	–	1	–	10	µA

NOISE CHARACTERISTICS

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = +25°C		Unit
				Typ	Max	
V _{OLP} (Note 3)	Quiet Output Maximum Dynamic V _{OL}	C _L = 50 pF	5.0	–	1.0	V
V _{OLV} (Note 3)	Quiet Output Minimum Dynamic V _{OL}	C _L = 50 pF	5.0	–	1.0	V
V _{OHV} (Note 3)	Quiet Output Minimum Dynamic V _{OH}	C _L = 50 pF	5.0	–	4.0	V
V _{IHD} (Note 3)	Minimum HIGH Level Dynamic Input Voltage	C _L = 50 pF	5.0	–	3.5	V
V _{ILD} (Note 3)	Maximum LOW Level Dynamic Input Voltage	C _L = 50 pF	5.0	–	1.5	V

3. Parameter guaranteed by design.

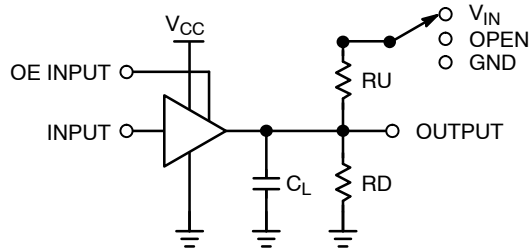
AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = +25°C			T _A = -40 to +85°C		Unit
				Min	Typ	Max	Min	Max	
t _{PLH} t _{PHL}	Propagation Delay A _n to Y _n (Figure 4, 6)	C _L = 15 pF R _D = 1 MΩ S ₁ = OPEN	1.8 ±0.15	–	–	12.0	–	13.0	ns
			2.5 ±0.2	–	–	7.5	–	8.0	
			3.3 ±0.3	–	–	5.2	–	5.5	
			5.0 ±0.5	–	–	4.5	–	4.8	
		C _L = 50 pF, R _D = 500 Ω S ₁ = OPEN	3.3 ±0.3	–	–	5.7	–	6.0	
			5.0 ±0.5	–	–	5.0	–	5.3	
t _{OSLH} t _{OSHL}	Output to Output Skew (Note 4) (Figure 4, 6)	C _L = 50 pF, R _D = 500 Ω S ₁ = OPEN	3.3 ±0.3	–	–	1.0	–	1.0	ns
			5.0 ±0.5	–	–	0.8	–	0.8	
t _{PZL} t _{PZH}	Output Enable Time (Figure 4, 6)	C _L = 50 pF R _D , R _U = 500 Ω S ₁ = GND for t _{PZH} S ₁ = V _I for t _{PZL} V _I = 2 x V _{CC}	1.8 ±0.15	–	–	14.0	–	15.0	ns
			2.5 ±0.2	–	–	8.5	–	9.0	
			3.3 ±0.3	–	–	6.2	–	6.5	
			5.0 ±0.5	–	–	5.5	–	5.8	
t _{PLZ} t _{PHZ}	Output Disable Time (Figure 4, 6)	C _L = 50 pF R _D , R _U = 500 Ω S ₁ = GND for t _{PZH} S ₁ = V _I for t _{PZL} V _I = 2 x V _{CC}	1.8 ±0.15	–	–	12.0	–	13.0	ns
			2.5 ±0.2	–	–	8.0	–	8.5	
			3.3 ±0.3	–	–	5.7	–	6.0	
			5.0 ±0.5	–	–	4.7	–	5.0	
C _{IN}	Input Capacitance		0	–	2.5	–	–	–	pF
C _{OUT}	Output Capacitance		5.0	–	4	–	–	–	pF
C _{PD}	Power Dissipation Capacitance (Figure 5)	(Note 5)	3.3	–	10	–	–	–	pF
			5.0	–	12	–	–	–	

4. Parameter guaranteed by design. t_{OSLH} = |t_{PLHmax} – t_{PLHmin}|; t_{OSHL} = |t_{PHLmax} – t_{PHLmin}|.

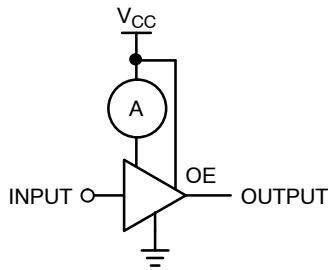
5. C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. (see Figure 5) C_{PD} is related to I_{CCD} dynamic operating current by the expression:
I_{CCD} = (C_{PD}) (V_{CC}) (f_{IN}) + (I_{CCstatic}).

AC Loading and Waveforms



C_L includes load and stray capacitance
Input PRR = 1.0 MHz; $t_W = 500$ ns

Figure 4. AC Test Circuit



Input = AC Waveform; $t_r = t_f = 1.8$ ns;
PRR = 10 MHz; Duty Cycle = 50%.

Figure 5. I_{CCD} Test Circuit

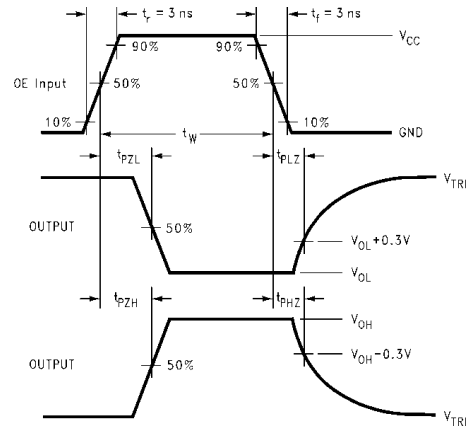
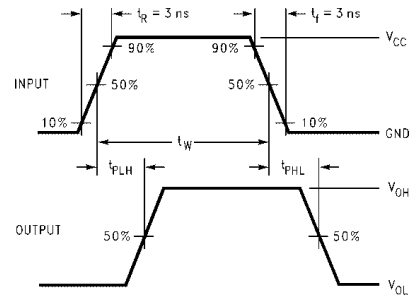


Figure 6. AC Waveforms

ORDERING INFORMATION

Order Number	Top Mark	Package	Shipping [†]
NC7WZ126K8X	WZ26	8-Lead US8, JEDEC MO-187, Variation CA 3.1 mm Wide	3000 / Tape & Reel
NC7WZ126L8X	T6	8-Lead MicroPak, 1.6 mm Wide (Pb-Free)	5000 / Tape & Reel

DISCONTINUED (Note 7)

NC7WZ126L8X-L22185	T6	8-Lead MicroPak, 1.6 mm Wide (Pb-Free)	5000 / Tape & Reel
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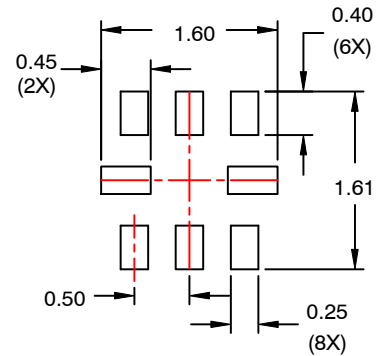
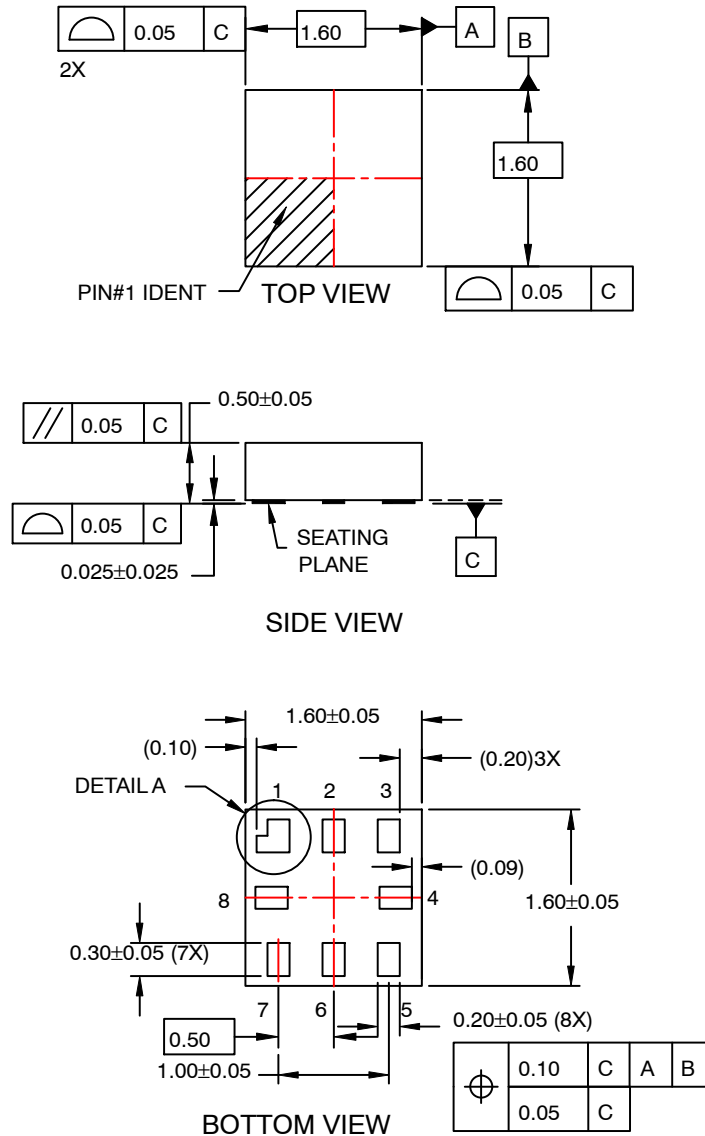
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

6. Pb-Free package per JEDEC J-STD-020B.

7. **DISCONTINUED:** This device is not recommended for new design. Please contact your onsemi representative for information. The most current information on this device may be available on www.onsemi.com.

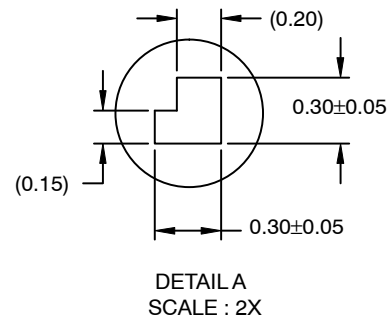
UQFN8 1.6X1.6, 0.5P
CASE 523AY
ISSUE O

DATE 31 AUG 2016



NOTES:

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- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.

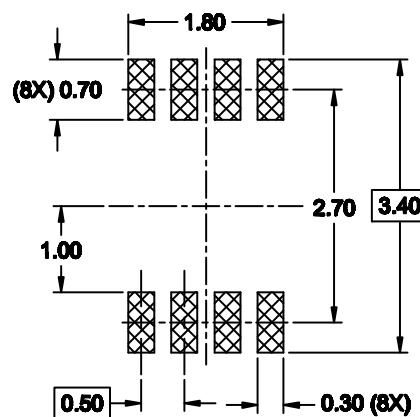
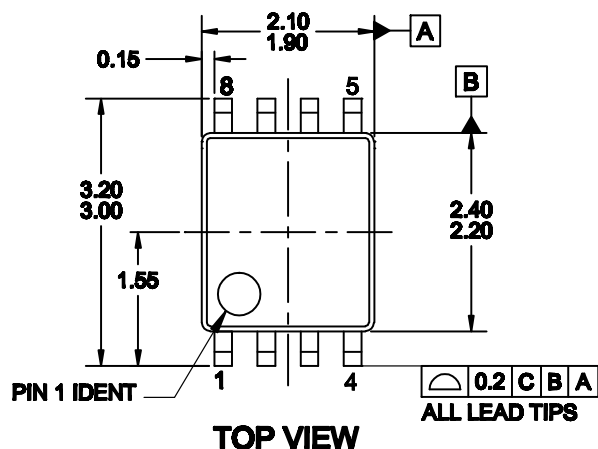


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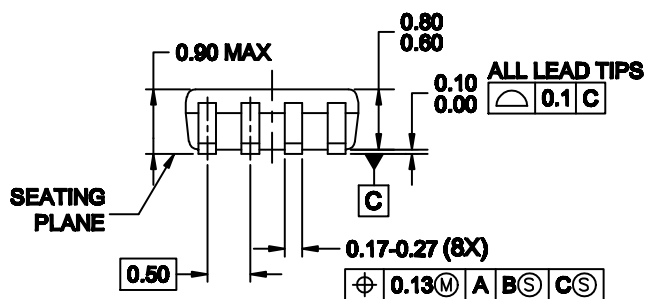
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US8
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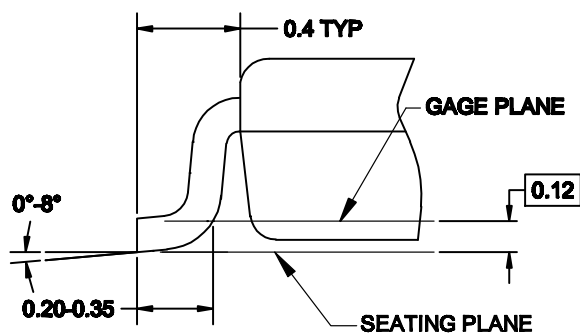
DATE 31 DEC 2016



RECOMMENDED LAND PATTERN



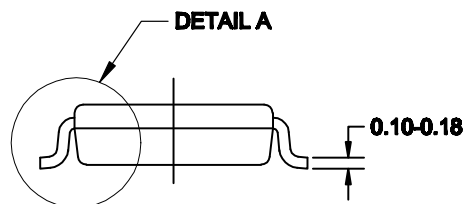
SIDE VIEW



DETAIL A

NOTES:

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